

	Application No.	Applicant(s)	
Mada a CAller al 194	10/681,747	KARNEZOS, MARCOS	
Notice of Allowability	Examiner	Art Unit	
	Roy K Potter	2822	
Th MAILING DATE of this communication appeall claims being allowable, PROSECUTION ON THE MERITS IS herewith (or previously mailed), a Notice of Allowance (PTOL-85) NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RID of the Office or upon petition by the applicant. See 37 CFR 1.313	(OR REMAINS) CLOSED in this a or other appropriate communication GHTS. This application is subject	pplication. If not included on will be mailed in due course. THIS	s ativ
1. $igotimes$ This communication is responsive to <u>the amendment of 11.</u>	<u>/4/2004</u> .		
2. The allowed claim(s) is/are <u>1-20,41 and 42</u> .			
3. $igotimes$ The drawings filed on <u>04 November 2004</u> are accepted by	the Examiner.		
4. ☐ Acknowledgment is made of a claim for foreign priority una) ☐ All b) ☐ Some* c) ☐ None of the: 1. ☐ Certified copies of the priority documents have 2. ☐ Certified copies of the priority documents have 3. ☐ Copies of the certified copies of the priority documents have International Bureau (PCT Rule 17.2(a)). * Certified copies not received: Applicant has THREE MONTHS FROM THE "MAILING DATE" noted below. Failure to timely comply will result in ABANDONM THIS THREE-MONTH PERIOD IS NOT EXTENDABLE.	been received. been received in Application No. cuments have been received in thi of this communication to file a repl ENT of this application.	s national stage application from th y complying with the requirements R'S AMENDMENT or NOTICE OF	
INFORMAL PATENT APPLICATION (PTO-152) which give	•	ration is deficient.	
 CORRECTED DRAWINGS (as "replacement sheets") mus (a) ☐ including changes required by the Notice of Draftspers 		0-948) attached	
1) hereto or 2) to Paper No./Mail Date		y o roy allaonou	
(b) ☐ including changes required by the attached Examiner's Paper No./Mail Date	s Amendment / Comment or in the	Office action of	
Identifying indicia such as the application number (see 37 CFR 1. each sheet. Replacement sheet(s) should be labeled as such in t			
 DEPOSIT OF and/or INFORMATION about the deposit attached Examiner's comment regarding REQUIREMENT 			
Attachm nt(s) 1. ⊠ Notice of References Cited (PTO-892)	5. Notice of Informal	Patent Application (PTO-152)	
2. Notice of Draftperson's Patent Drawing Review (PTO-948)	6. Interview Summar		
 Information Disclosure Statements (PTO-1449 or PTO/SB/0 Paper No./Mail Date	·		
of Biological Material	9. Other	Roy Potter Primary Examiner Technology Center 2800	

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EXAMINER'S AMENDMENT

Election

Applicant's election without traverse of claims 1 – 20 and 41 - 42 in the reply filed on 11/1/2004 is acknowledged.

An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

The application has been amended as follows:

Nonelected claims 21-40 have been canceled. These claims were not elected in the election made without traverse on 11/1/2004.

Reason's for Allowance

The following is an examiner's statement of reasons for allowance:

The prior art does not teach or suggest the recited multi-package module comprising stacked first and second packages, each including a die attached to a substrate, where one is a flip-chip ball grid array package and the other is inverted and the two stacked substrates are interconnected by wire bonds.

Akram et al., U.S. Patent No. 5,994,166 discloses a method or constructing stacked packages. As shown in Figure 1, the substrate 116 has die 128 attached to it.

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Die 128 is wire bonded to the substrate. Substrate 140 has die162 attached to it. Die 162 is a flip-chip. The substrates are arranged in a stacked arrangement.

Akram does not disclose that the substrates are interconnected by wire bonding.

The substrates are instead interconnected by electrical connections 148.

Hsu et al., U.S. Patent No. 6,462,421 discloses a multichip module. As shown in figure 4, the module comprises first die 210 and second die 230 each attached to substrate.

Kaul et al., U.S. Patent no 5,444,296, discloses a ball grid array package.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Roy K Potter whose telephone number is 571 272 1842. The examiner can normally be reached on M-F.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Roy K Potter Primary Examiner Art Unit 2822